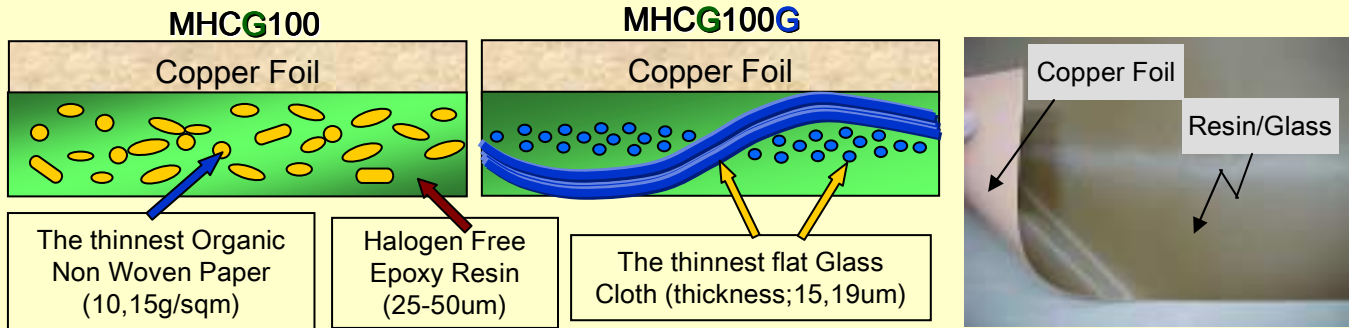


Newly Launched The Thinnest Dielectric Materials

MHCG100 series

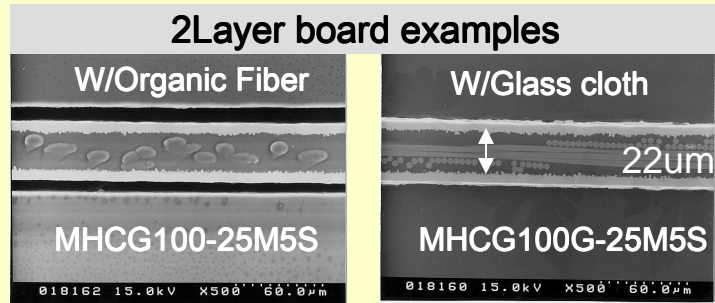


Structure RCF + reinforced materials (The first in the world)



Features Thin, Strong, Light, Flex (薄く、強く、軽く、柔らかく)

- Very thin dielectric(20-30um) is available
- Environmentally friendly halogen free material
- Excellent Uniformity of thickness and flatness
- Higher elastic modulus than RCC
- Excellent laser drillability (2-3 shots by CO2)
- Easy to form filled via
- Low CTE



Characteristics

			MHCG100	MHCG100G	MR600
Resin Thickness um			25- 50	25- 50	40- 80
Copper Foil			3FC- VLP/ MicroThin		
Tg	DMA	Celsius	190- 200	190- 200	180
Peel Strength	JIS6481	KN/ m	1.0	1.0	1.0
Thermal Stress1	260C	sec	>300	>300	>300
Young's Modulus	JIS2318	Gpa	7	12	3
CTE (X/ Y)	IPC TM650	PPM/ C	20	15	70
Migration I / S=50/ 50	85C/ 85% 35V	Ohm	>10 ⁸	>10 ⁸	>10 ⁸
Flammability	UL 94	-	V- 0 VTM- 0	V- 0 VTM- 0	V- 0
Dielectric Constant	IPC TM650	1GHz	3.3	4	3.4
Dissipation Factor	IPC TM650	1GHz	0.019	0.019	0.023

MR600; High Tg RCF of Mitsui Mining and Smelting Co. Ltd.